

Memory Product Specification

DDR2-667 SO-DIMM

Description

The Module is DDR2-667 CL5 Small Outline Memory module. The Module density from 512MB to 2GB, it consists 64/128Mx8 bit DDR2-667MHz Synchronous DRAMs in FBGA packages, Memory Module intended for mounting into 200-pin edge connector sockets. The electrical and mechanical specifications are as follows.

Features

- JEDEC Standard
- DDR2 Speed Grade : 667Mbps
- SO-DIMM : 200-pin
- Memory Organization : x8 , x16 FBGA DRAM chip
- DDR2 DRAM interface : SSTL_18
- CAS latency : 5-5-5
- Bandwidth : 5300MB/s
- VDD voltage : 1.8+-0.1V
- VDDQ voltage : 1.8+-0.1V
- Serial presence detect with EEPROM.
- PCB height : **1.181 inch**
- RoHS Compliant
- Application : NoteBook